

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Wafer size change (6-to-8 inch) for ADI products in S12 process
Publication Date:	27-Apr-2023
Effectivity Date:	30-Jul-2023 <i>(the earliest date that a customer could expect to receive changed material)</i>
Revision Description:	

Description Of Change:

-
 Wafer size change for ADI products in current S12 process
 Current 6-inch wafer size fabricated at ADI's Beaverton/Oregon foundry (ADBN)

Reason For Change:

-
 ADI is moving to the 8-inch process to ensure adequate capacity for supply continuity.
 ADI has been shipping products fabricated on 8-inch wafers in mass production from ADBN since 2010.

The 8-inch flow reliability/qualification report is attached.

The Form/Fit/Function of the devices is unchanged.

Impact of the change (positive or negative) on fit, form, function & reliability:

Product Identification (this section will describe how to identify the changed material):

Summary of Supporting Information:

Supporting Documents:

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Impacted items, see csv PN listing in PCN Zip file